

Features

- ⊗ Frequency range : 24MHz to 66MHz
- ⊗ Ultra compact and thin
- ⊗ AuSn sealing, ceramic SMD package
- ⊗ External dimensions (mm)
L : 1.6 x W : 1.2 x H : 0.35
- ⊗ RoHS compliant & Pb free

Applications

- ⊗ BT, BLE, W-LAN, NFC
- ⊗ SiP modules
- ⊗ Mobile phone, Wearables
- ⊗ Internet of Things (IoT)
- ⊗ Portable consumer products

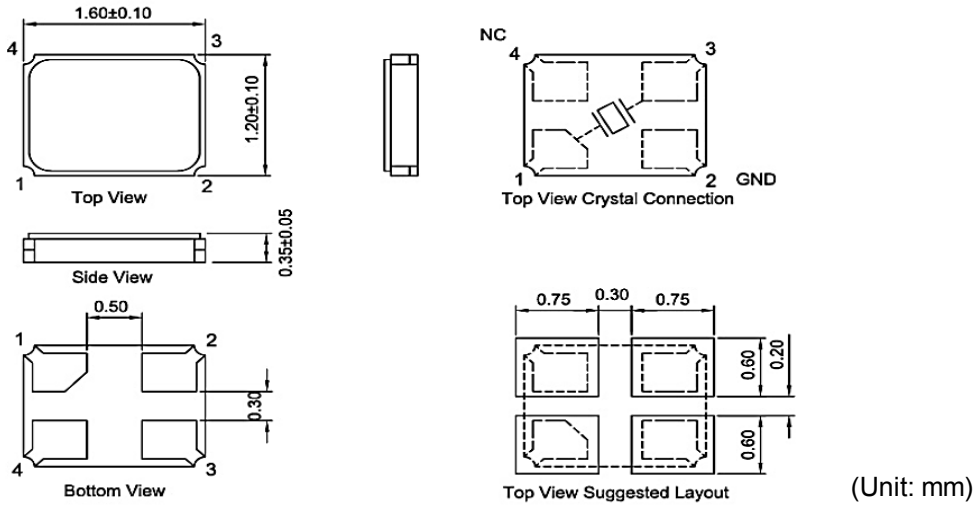
Electrical Characteristics

Item		8Q	Conditions
Frequency Range	F_0	24MHz ~ 66MHz	
Frequency Tolerance	F_{tol}	$\pm 30\text{ppm}$, $\pm 20\text{ppm}$, $\pm 10\text{ppm}$	at 25°C
Frequency Stability over Operating Temperature Range (refer to 25°C)	F_{stab}	$\pm 30\text{ ppm}$	-20°C ~ +70°C
		$\pm 20\text{ ppm}$	
		$\pm 10\text{ ppm}$	
		$\pm 10\text{ ppm}$	-30°C ~ +85°C
		$\pm 30\text{ ppm}$	-40°C ~ +85°C
		$\pm 20\text{ ppm}$	
Operating Temperature Range	T_{OTR}	-20°C ~ +70°C	
		-40°C ~ +85°C	
		-40°C ~ +125°C	
Shunt Capacitance	C_0	3pF Max.	
Drive Level	D_L	1 ~ 200 μ W (50 μ W Typ.)	
Load Capacitance	C_L	6pF, 8pF, 10pF, 12pF	
Aging	F_{aging}	$\pm 3\text{ ppm Max.}$	at 25°C $\pm 3^\circ\text{C}$, first year
Storage Temperature Range	T_{STR}	-55°C ~ +125°C	

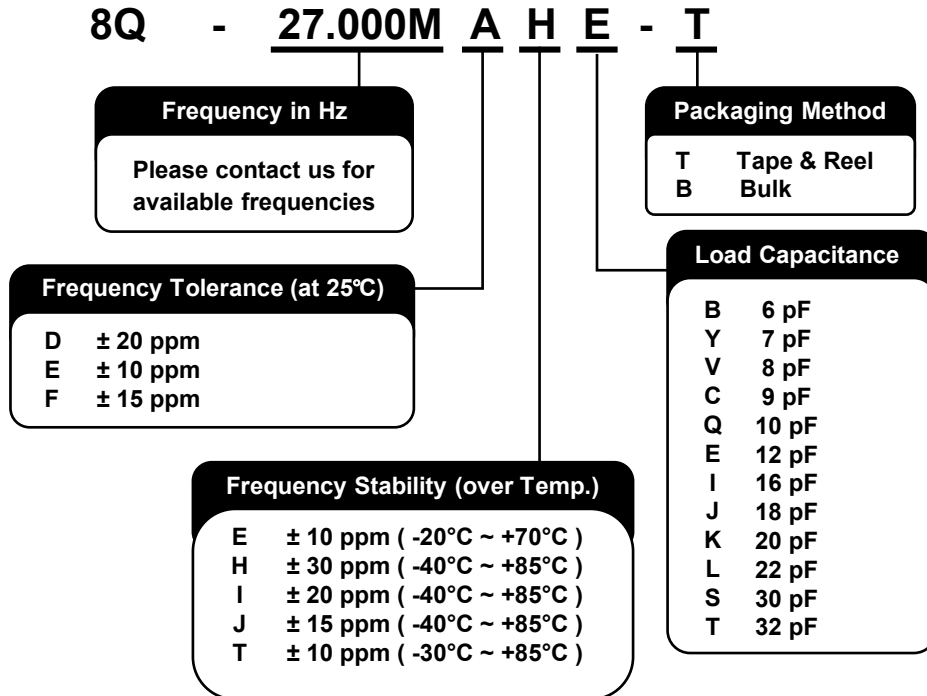
Motional Resistance (ESR)

Fundamental	
24 ~ 30 MHz	100 Ω Max.
30 ~ 66 MHz	80 Ω Max.

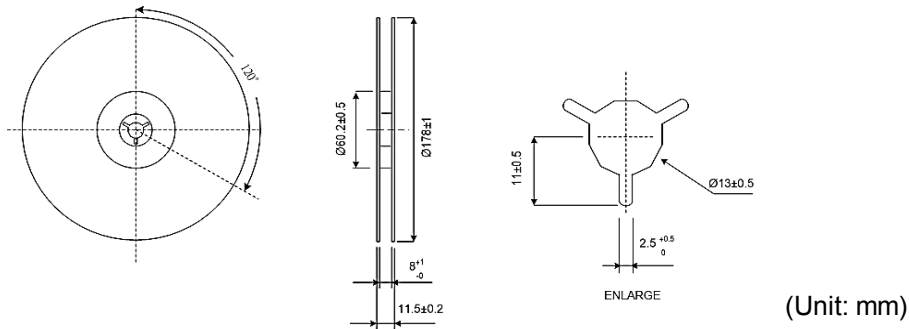
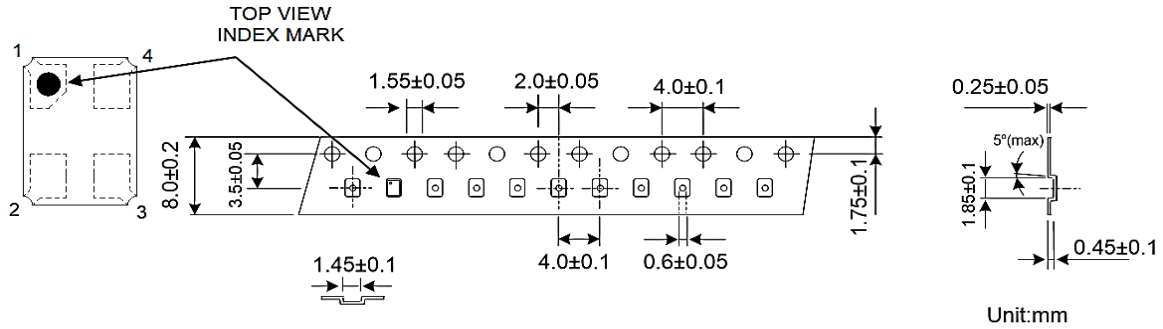
Dimensions



Ordering Information



Packing



Reflow Profile

Solder melting point : 220°C ± 10°C, 60 sec. Min.

Peak temperature : 260°C ± 10°C, 10 sec. Min.

